

EN: This Datasheet is presented by the manufacturer.

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SCLS307B- JANUARY 1996 - REVISED JANUARY 2003

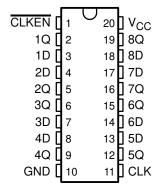
- Wide Operating Voltage Range of 2 V to 6 V
- **Outputs Can Drive Up To 10 LSTTL Loads**
- Low Power Consumption, 80-µA Max ICC
- Typical $t_{nd} = 12 \text{ ns}$
- ±4-mA Output Drive at 5 V
- Low Input Current of 1 µA Max
- **Eight Flip-Flops With Single-Rail Outputs**
- **Clock Enable Latched to Avoid False** Clocking
- **Applications Include:**
 - Buffer/Storage Registers
 - Shift Registers
 - Pattern Generators

description/ordering information

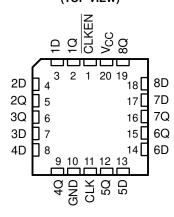
These devices are positive-edge-triggered octal D-type flip-flops with an enable input. The 'HC377 devices are similar to the 'HC273 devices, but feature a latched clock-enable (CLKEN) input instead of a common clear.

Information at the data (D) inputs meeting the setup time requirements is transferred to the Q outputs on the positive-going edge of the clock (CLK) pulse, if CLKEN is low. Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going pulse. When CLK is at either the high or low level, the D input has no effect at the output. These devices are designed to prevent false clocking by transitions at CLKEN.

SN54HC377...J OR W PACKAGE SN74HC377 . . . DW. N. OR NS PACKAGE (TOP VIEW)



SN54HC377 . . . FK PACKAGE (TOP VIEW)



ORDERING INFORMATION

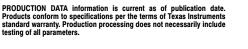
TA	PACKAG	GET	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube	SN74HC377N	SN74HC377N
4000 to 0500	COIC DW	Tube	SN74HC377DW	110077
–40°C to 85°C	SOIC - DW	Tape and reel	SN74HC377DWR	HC377
	SOP - NS	Tape and reel	SN74HC377NSR	HC377
	CDIP – J	Tube	SNJ54HC377J	SNJ54HC377J
–55°C to 125°C	CFP – W	Tube	SNJ54HC377W	SNJ54HC377W
	LCCC - FK	Tube	SNJ54HC377FK	SNJ54HC377FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



testing of all parameters.

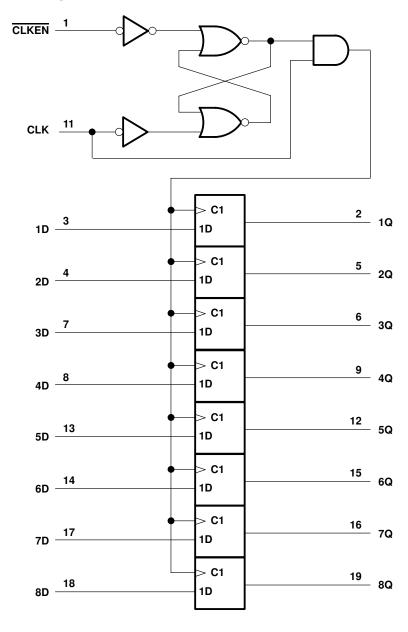
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



FUNCTION TABLE (each flip-flop)

ll l	INPUTS								
CLKEN	CLK	D	Q						
Н	Х	Χ	Q ₀						
L	\uparrow	Н	Н						
L	\uparrow	L	L						
X	L	Χ	Q ₀						

logic diagram (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (s		
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_O$		
Continuous output current, I_O ($V_O = 0$ to V_{CC})		
Continuous current through V _{CC} or GND		
Package thermal impedance, θ _{JA} (see Note 2): DW package	 58°C/W
, <u> </u>	N package .	 69°C/W
	NS package	 60°C/W
Storage temperature range, T _{stg}		 to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

			SI	N54HC37	7	SN	174HC37	7	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage		2	5	6	2	5	6	V
		V _{CC} = 2 V	1.5			1.5			
VIH	High-level input voltage	$V_{CC} = 4.5 \text{ V}$	3.15			3.15			V
		$V_{CC} = 6 V$	4.2			4.2			
		V _{CC} = 2 V			0.5			0.5	
٧ _{IL}	Low-level input voltage	V _{CC} = 4.5 V			1.35			1.35	V
		$V_{CC} = 6 V$			1.8			1.8	
٧ _I	Input voltage		0		VCC	0		VCC	V
VO	Output voltage		0		VCC	0		VCC	V
		V _{CC} = 2 V			1000			1000	
Δt/Δν	Input transition rise/fall time	V _{CC} = 4.5 V			500			500	ns
		V _{CC} = 6 V			400			400	
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at VCC or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

SN54HC377, SN74HC377 OCTAL D-TYPE FLIP-FLOPS WITH CLOCK ENABLE

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				Т	A = 25°C	;	SN54H	C377	SN74H	C377	
PARAMETER	TEST CO	ONDITIONS	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	1.9	1.998		1.9		1.9		
		$I_{OH} = -20 \mu A$	4.5 V	4.4	4.499		4.4		4.4		
VOH	VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9		V
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
		$I_{OH} = -5.2 \text{ mA}$	6 V	5.48	5.8		5.2		5.34		
			2 V		0.002	0.1		0.1		0.1	
		I _{OL} = 20 μA	4.5 V		0.001	0.1		0.1		0.1	
VOL	VI = VIH or VIL		6 V		0.001	0.1		0.1		0.1	V
		I _{OL} = 4 mA	4.5 V		0.17	0.26		0.4		0.33	
		$I_{OL} = 5.2 \text{ mA}$	6 V		0.15	0.26		0.4		0.33	
lį	$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000		±1000	nA
ICC	$V_I = V_{CC}$ or 0,	IO = 0	6 V			8		160		80	μΑ
Ci			2 V to 6 V		3	10		10		10	pF

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

			,,	T _A = 2	25°C	SN54H	C377	SN74H	C377														
			vcc	MIN	MAX	MIN	MAX	MIN	MAX	UNIT													
			2 V		5		3		4														
f _{clock}	fclock Clock frequency				25		16		20	MHz													
					29		19		23														
			2 V	100		150		125															
t _w	Pulse duration, CLK high o	r low	4.5 V	20		30		25		ns													
		6 V	17		25		21																
		D CLKEN high or low	2 V	100		150		125															
			4.5 V	20		30		25															
	0-1		6 V	17		25		21															
t _{su}	Setup time before CLK↑															2 V	100		150		125		ns
			4.5 V	20		30		25															
			6 V	17		25		21															
_		<u> </u>	CLKEN inactive or active, data	2 V	5		5		5		_												
th	Hold time after CLK↑			CLKEN inactive or active, data	CLKEN inactive or active, data	CLKEN inactive or active, data 4	CLKEN inactive or active, data 4	CLKEN inactive or active, data 4	CLKEN inactive or active, data 4	4.5 V	5		5		5		ns						
			6 V	5		5		5															

SN54HC377, SN74HC377 OCTAL D-TYPE FLIP-FLOPS WITH CLOCK ENABLE SCLS307B- JANUARY 1996 - REVISED JANUARY 2003

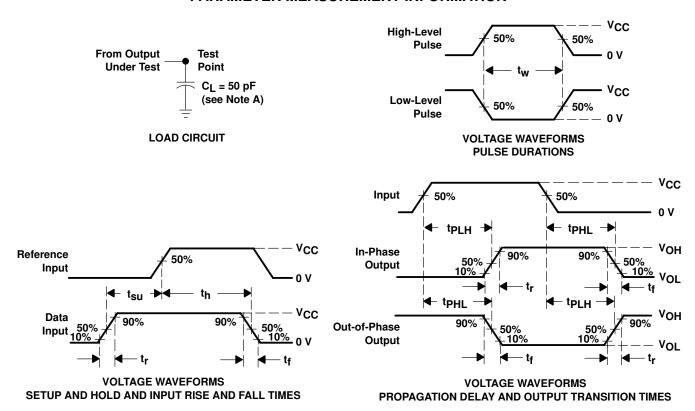
switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	,,	T,	4 = 25°C	;	SN54F	IC377	SN74H	IC377			
PARAMETER	(INPUT)	(OUTPUT)	(OUTPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	5	11		3		4				
f _{max}			4.5 V	25	54		16		20		MHz		
		6 V	29	64		19		23					
			2 V		56	160		240		200			
t _{pd}	CLK	Any	4.5 V		15	32		48		40	ns		
·			6 V		12	27		41		34			
			2 V		38	75		110		95			
t _t		Any	4.5 V		8	15		22		19	ns		
			6 V		6	13		19		16			

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per flip-flop	No load	30	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \ \Omega$, $t_f = 6 \ ns$, $t_f = 6 \ ns$.
- C. For clock inputs, f_{max} is measured when the input duty cycle is 50%.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms







9-Mar-2021

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-87807012A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 87807012A SNJ54HC 377FK	Samples
5962-8780701RA	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8780701RA SNJ54HC377J	Samples
SN54HC377J	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54HC377J	Samples
SN74HC377DW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC377	Samples
SN74HC377DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC377	Samples
SN74HC377N	ACTIVE	PDIP	N	20	20	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC377N	Samples
SN74HC377NE4	ACTIVE	PDIP	N	20	20	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC377N	Samples
SN74HC377NSR	ACTIVE	SO	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC377	Samples
SNJ54HC377FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 87807012A SNJ54HC 377FK	Samples
SNJ54HC377J	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8780701RA SNJ54HC377J	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".





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Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54HC377, SN74HC377:

Catalog: SN74HC377

Military: SN54HC377

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

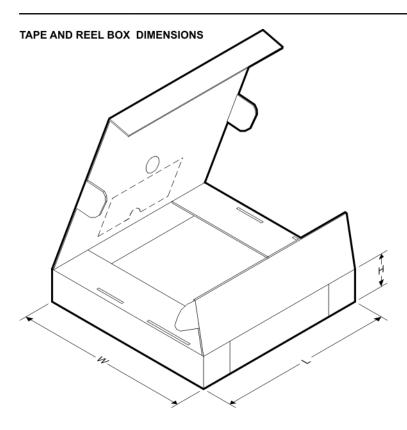
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC377DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74HC377NSR	SO	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1

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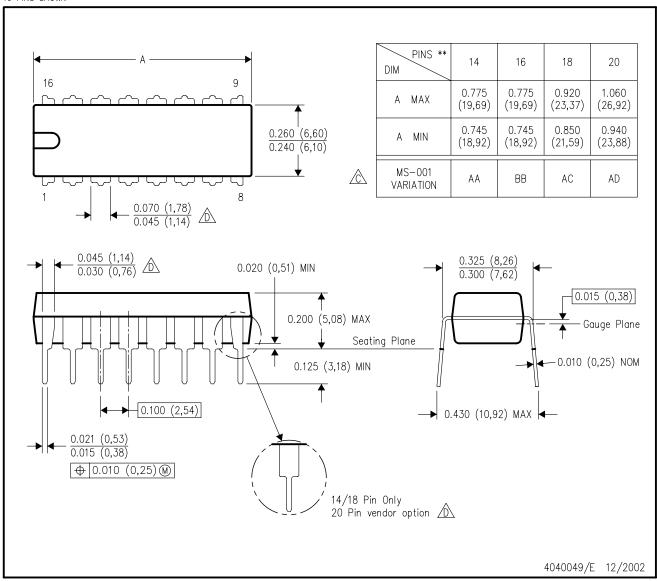
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC377DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74HC377NSR	SO	NS	20	2000	367.0	367.0	45.0

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

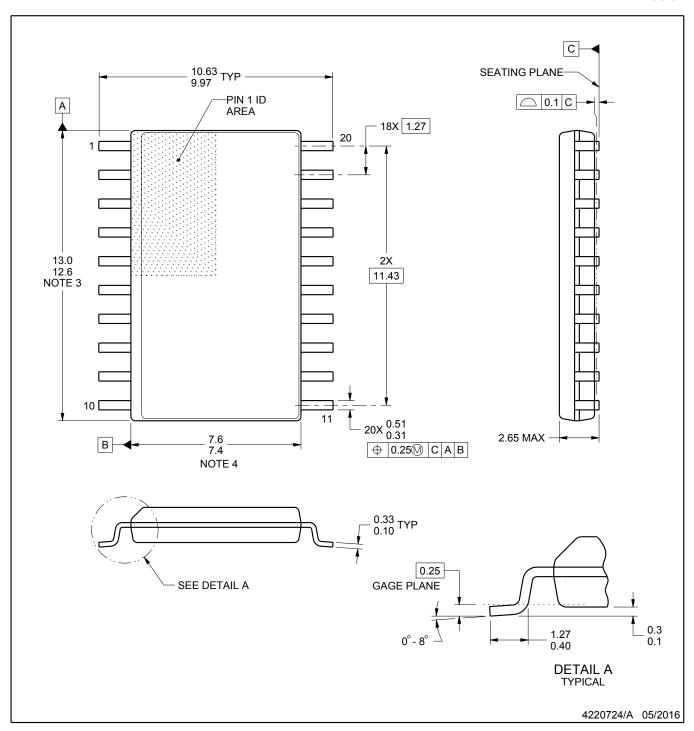


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOIC



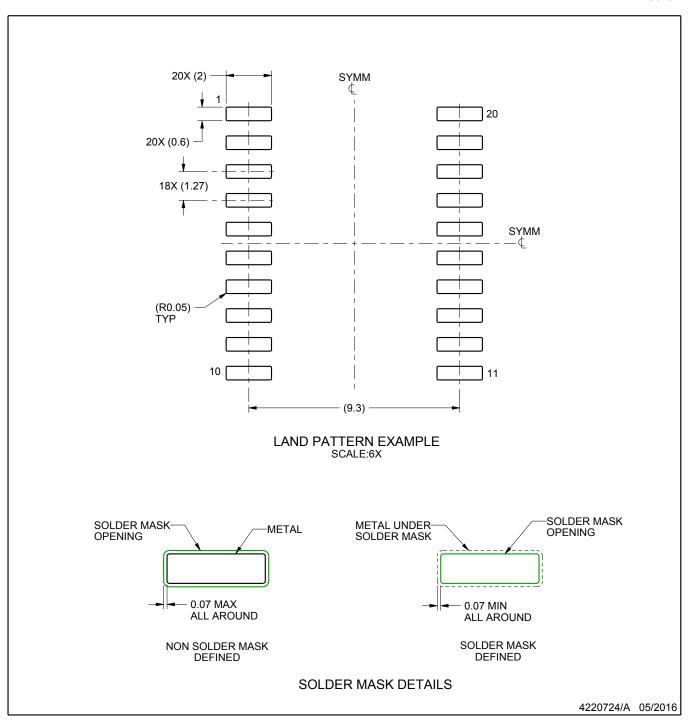
- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



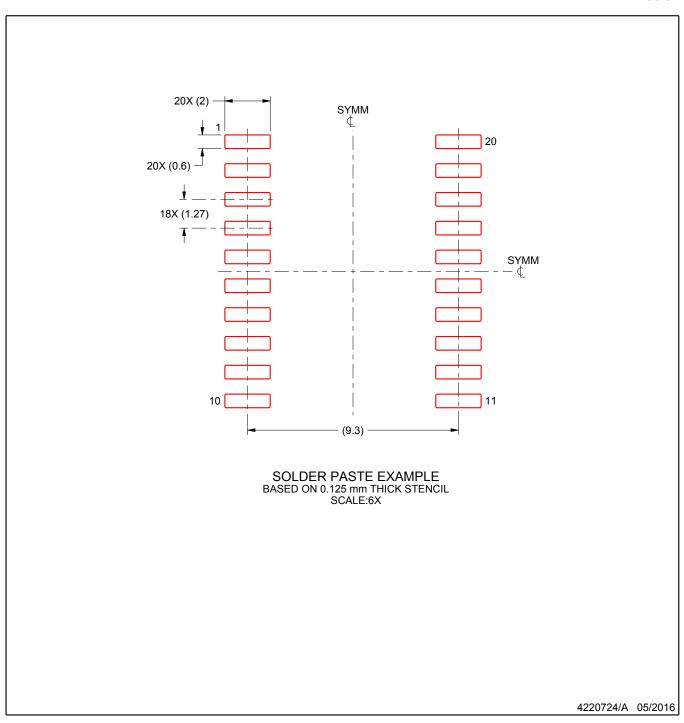
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

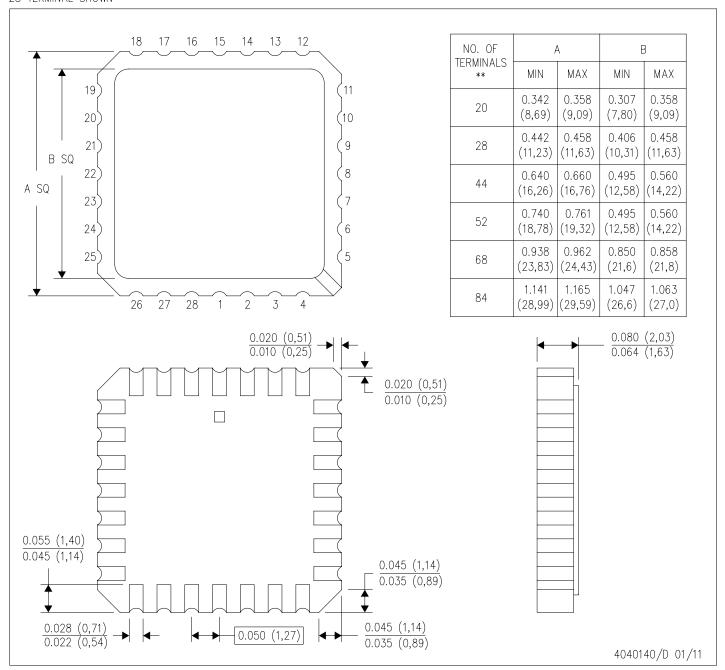
- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004

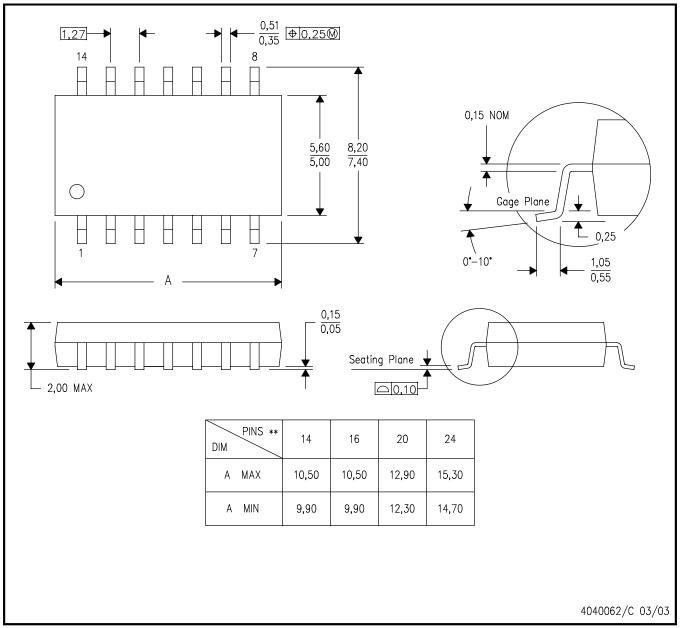


MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

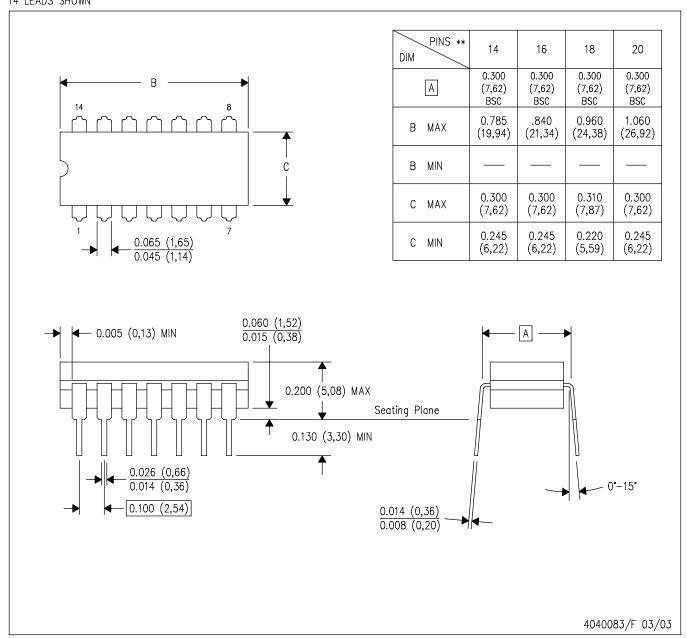
PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

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